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MT53D1024M32D4DT-046 AAT

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Specs

Orderable Parts for: MT53D1024M32D4DT-046 AAT

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	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT53D1024M32D4DT-046 AAT:D	Production	N/A	D9WMH	N/A	N/A	No		N/A

Detailed Specifications

Technology	LPDDR4	Density	32Gb	Part Status	Production	RoHS	Yes
Depth	1024Mb	Width	x32	Voltage	1.1V/0.6V	Package	WFBGA
Pin Count	200-ball	Clock Rate	2133 MHz	Data Rate	DDR4-4166	Cycle Time	
Op. Temp.	-40C to +105C	Brand	Micron				

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions.

File Type: (PDF)

Updated: 12/2018

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China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

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Technical Notes

[SEARCH \(82\) TECHNICAL NOTES](#)

Technical Notes

[TN-41-17: DDR3L MT41K512M16 SDP to DDP Migration Guide \(PDF\)](#)

[DDR3 SDRAM
DRAM](#)

(TN-41-17) This technical note explains how to migrate a PCB design that uses a Micron 8Gb DDR3L product from a 90 series single-die 96-ball package to a 100 series dual-die 96- ball package.

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Technical Notes

[TN-00-01: Moisture Sensitivity of Plastic Packages \(PDF\)](#)

[DDR SDRAM
DDR2 SDRAM
DDR3 SDRAM
DDR3L-RS
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(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

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